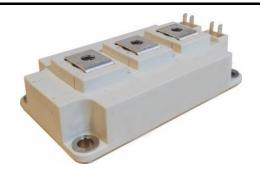


QMFF400R12EFF 1200V 400A IGBT Module

Electrical Features

- Trench/Fieldstop IGBT
- Half-bridge
- Standard package
- High short circuit capability
- Including anti-parallel FWD



Typical Applications

- Frequency converter
- UPS
- High Power Converters
- Motor Drives
- Wind Turbines

IGBT, Inverter

Maximu	m Rated Values						
Symbol	Item	Conditions			Rating		Unit
IGBT							
V _{CES}	Collector-emitter voltage	$T_{vj}=25$ °C			1200		V
$ m V_{GES}$	Gate-emitter voltage	-			±20		V
$I_{\rm C}$	Collector current,DC	$T_{\rm C}=100^{\circ}{\rm C}, T_{\rm vj}=175^{\circ}$	PC .		400		A
I_{CRM}	Repetitive peak collector current	$t_p=1$ ms	t _p =1ms			800	
t_{SC}	Short circuit withstand time	V _{GE} =15V, V _{CC} =600V, T _{vj} ≤150°C			1	0	μs
P _{tot}	Total power dissipation	T _C =25°C,T _{vj} =175°C			2419		W
Characte	eristics Values						
Symbol	Item	Conditions			Values		Unit
IGBT				Min.	Тур.	Max.	
I _{CES}	Collector-emitter cut-off current	V _{CE} =1200V,V _{GE} =0V,T _{vj} =25°C		-	-	1	mA
I _{GES}	Gate leakage current	V _{CE} =0V,V _{GE} =20V,T _{vj} =25°C		-	-	250	nA
$V_{\text{GE(th)}}$	Gate-emitter threshold voltage	$I_C=16\text{mA}, V_{CE}=V_{GE}, T_{vj}=25^{\circ}\text{C}$		5.0	6.0	7.0	
	Collector-emitter saturation voltage	I _C =400A V _{GE} =15V	T _{vj} =25°C	-	1.90	2.4	\mathbf{V}
V_{CEsat}			T _{vj} =125°C	-	1.90	-	_ v
			T _{vj} =150°C	-	1.93	-	
Cies	Input capacitance	V _{CE} =25V,V _{GE} =0V		-	31.3	-	nF
Cres	Reverse transfer capacitance	$f=1MHz,T_{vj}=25^{\circ}C$		-	0.95	-	III
Q_{G}	Gate charge	V _{CC} =600V, I _C =400A, V _{GE} =15V		-	2.4	-	uС
R_{g}	Internal gate resistance	T_{vj} =25°C		-	0.43	-	Ω



t _{d(on)}			T _{vj} =25°C	-	88	-	
	Turn-on delay time		$T_{vj}=125$ °C	-	156	-	
			T _{vj} =150°C	-	156	-	
			T _{vj} =25°C	-	117	-	
$t_{\rm r}$	Rise time	$V_{CC} = 600V$,	T _{vj} =125°C	-	163	-	
		I _C =400A,	T _{vj} =150°C	-	169	-	
$t_{ m d(off)}$		$V_{GE}=\pm 15V$,	T _{vj} =25°C	-	498	-	ns
	Turn-off delay time	$R_{G(on)}=2.5 \Omega$	T _{vj} =125°C	-	924	-	1
		$R_{G(off)}=2.5 \Omega$,	T _{vj} =150°C	-	931	-	
		L _{load} =100uH	T _{vj} =25°C	-	170	-	
$t_{\rm f}$	Fall time	di/dt=5390A/μs	T _{vj} =125°C	-	270	-	
		(T _{vj} =150°C)	T _{vj} =150°C	-	296	-	
		du/dt=2546V/μs	$T_{vj}=25$ °C	-	27.8	-	
E_{on}	Turn-on energy (per pulse)	(T _{vj} =150°C)	$T_{vi}=125$ °C	-	86.3	-	
			$T_{vj}=150$ °C	-	93.3	-	
			$T_{vj}=25$ °C	-	38.9	-	mJ
E_{off}	Turn-off energy (per pulse)		$T_{vj}=125$ °C	-	64.8	-	
011	ram on energy (per paise)		$T_{vj}=150$ °C	_	67.4	_	_
R _{thJC}	Thermal resistance, junction to case	per IGBT	1 5	_	0.062	-	K/W
R _{thCH}	Thermalresistance, case to heatsink	per IGBT/ λgrease	=1W/(m·K)	-		_	K/W
T _{vjop}	Temperature under switching		-40			150	°C
1 vjop	conditions			-40		150	
Diode,	Inverter						
Maximu	m Rated Values						
Symbol	Item	Conditions Rating					Unit
V_{RRM}	Repetitive peak reverse voltage	$T_{vj}=25$ °C			12	00	V
I_{F}	Forward current,DC					400	
I_{FRM}	Repetitive peak forward current	$t_p=1$ ms	t _p =1ms				A
Charact	eristic Values		_				
		$I_F=400A$	$T_{vj}=25$ °C	-	1.90	2.4	
V_{F}	Continuous forward voltage	$V_{GE}=0V$	$T_{vj}=125$ °C	-	1.35	-	V
		V GE-U V	T _{vj} =150°C	-	1.30	-	
			T _{vj} =25°C	-	248	-	
I_{RM}	Peak reverse recovery current		T _{vj} =125°C	-	328	-	A
			T _{vj} =150°C	-	364	-	1
t_{rr}			T _{vj} =25°C	-	171	-	
	Reverse recovery time	$V_R=600V$	$T_{vj}=125$ °C	-	388	-	ns
		$I_F=400A$	$T_{vj}=150$ °C	-	547	-	
Qr		$ di_F/dt=-4264A/\mu s$	$T_{vj}=25^{\circ}C$	_	31.6	_	
	Recovered charge	$(T_{vj}=150^{\circ}C)$	$T_{vj}=125$ °C	_	82.1		μC
			$T_{vj} = 150^{\circ}C$	_	101.9	_	["
			$T_{vj}=25^{\circ}C$	_	12.1	_	mJ
E_{rec}	Reverse recovery energy		T_{vj} =125°C	_	31.6	_	
Lrec	reverse recovery energy		$T_{vj}=123 \text{ C}$ $T_{vj}=150 \text{ °C}$		39.6		1
	T.	1	1 1 vi – 1 3 U C	-	1 37.0	-	1



R _{thJC}	Thermal resistance, junction to case	per diode	-	0.11	-	K/W
R_{thCH}	Thermalresistance, case to heatsink	per diode/ λgrease=1W/(m·K)	-		-	K/W
T_{vjop}	Temperature under switching conditions		-40		150	°C

Module

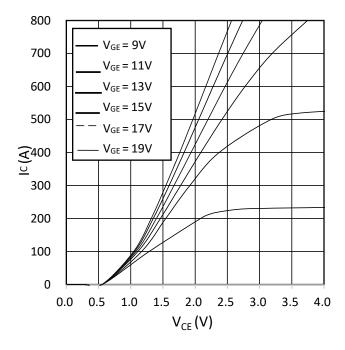
Symbol	Item	Conditions	Rating			Unit
V _{ISOL}	Isolation voltage	Terminals to baseplate, RMS,f=50Hz,t=1min	4000		V	
-	Material of module baseplate	-	Cu		-	
-	Internal isolation	Basic insulation(class 1, IEC 61140)	Al ₂ O ₃		-	
T_{stg}	Storage temperature	-	-40~125		°C	
Symbol	Item	C. Iv.		Values		
		Conditions	Min.	Тур.	Max.	
M	Mounting torque for module mounting	Screw M6	3.0	-	6.0	Nm
	Terminal connection torque	Screw M6	2.5	-	5.0	Nm
ds	Creepage distance	Terminal to terminal	-	23	-	
		Terminal to base plate	-	29	-	mm
da	Clearance	Terminal to terminal	-	11	-	
		Terminal to base plate	-	23	-	mm
m	Weight	-	-	315	-	g



utput characteristic IGBT, Inverter (typical)

$$I_{C} = f(V_{CE})$$

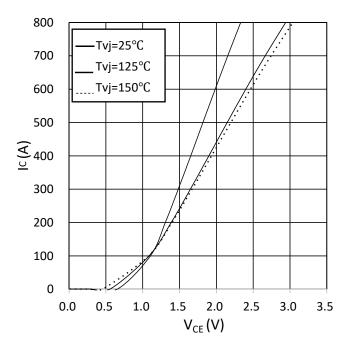
$$T_{\rm vj} = 150$$
°C



output characteristic IGBT, Inverter (typical)

$$I_C = f(V_{CE})$$

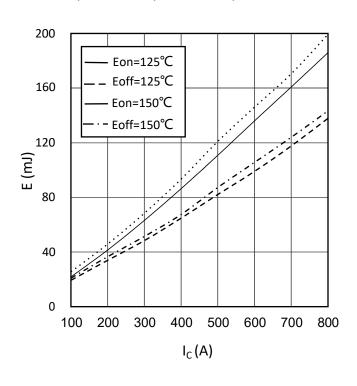
$$V_{GE} = 15 \, V$$



switching losses IGBT, Inverter(typical)

$$E_{on} = f(I_C), E_{off} = f(I_C)$$

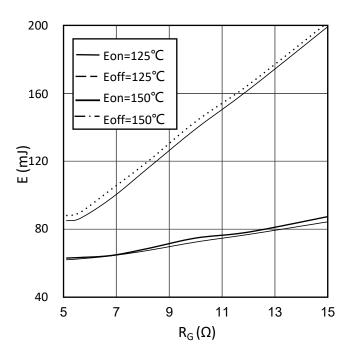
$$V_{GE}\!=\!\pm15V, R_{Gon}\!=5.1\Omega,\,R_{Goff}\!=5.1\Omega,\,V_{CE}\!\!=600V$$



switching losses IGBT, Inverter(typical)

$$E_{on} = f(R_G), E_{off} = f(R_G)$$

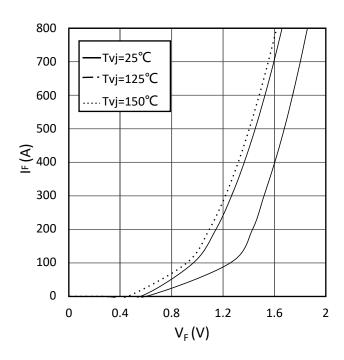
$$V_{GE} = \pm 15V, I_C = 400A, V_{CE} = 600V$$





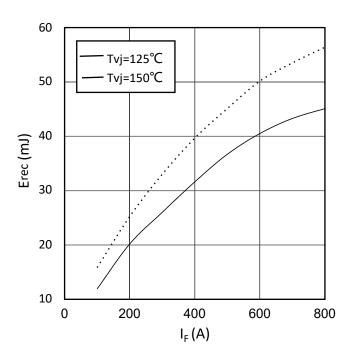
forward characteristic of Diode, Inverter (typical)

$$I_F = f(V_F)$$



switching losses Diode, Inverter (typical)

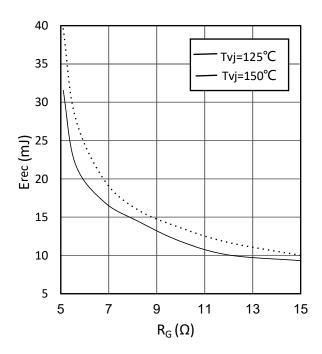
$$\begin{split} E_{rec} &= f(I_F) \\ R_{Gon} &= 5.1 \Omega, \, V_{CE} \!\!=\!\! 600 V \end{split} \label{eq:equation:equation:equation:equation}$$



switching losses Diode, Inverter (typical)

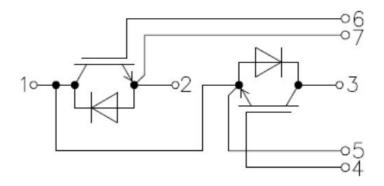
$$E_{rec} = f(R_G)$$

$$I_F = 400A, V_{CE} = 600V$$

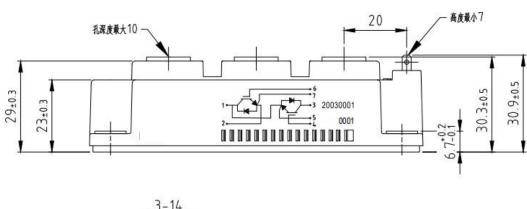


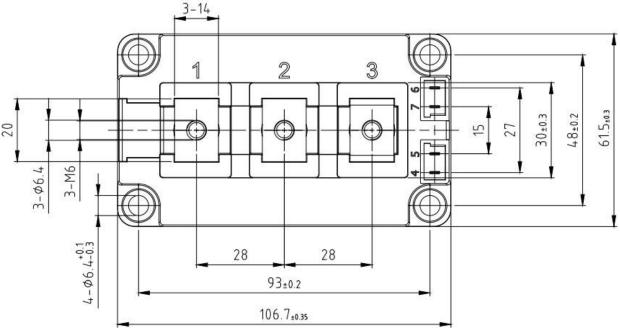


Circuit diagram headline



Package outlines (Unit: mm)







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